TOSHIBA CMOS Digital Integrated Circuits Silicon Monolithic

T6L37A

Source Driver for TFT LCD Panels

The T6L37A is a 64 gray-level and 300/309-channel-output source driver for TFT LCD panels. To meet the need for large-sized LCD panels, it allows a maximum operating frequency of 55 MHz. The device accepts 6-bit digital data inputs, which combined with the internal DA converter and 11 external power supplies allows display of up to 260,000 colors.

Based on high-speed CMOS, the T6L37A offers both low power consumption and high-speed operation. The T6L37A allows configuration of an XGA-or SVGA-compatible, high-performance TFT LCD module.

T6L37A USER AREA PITCH IN OUT Please contact Toshiba or an authorized Toshiba for the latest TCP specification and product lineup. TCP (Tape Carrier Package)

Features

Grayscale data : 18-bit digital (3 outputs × 6 bits)

parallel transfer method, selectable write direction.

• Panel drive outputs : 300/309 outputs, 64 gray levels, DAC system, reference analog voltage

• Fast operation : Max. 55 MHz

Power supply voltage : Digital power supply voltage 3.0 to 3.6 V

Analog power supply voltage 4.5 to 5.5 V

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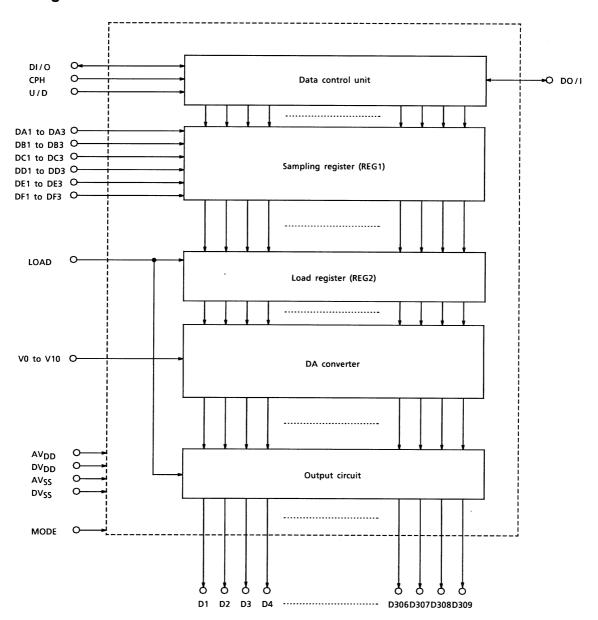
● Operating temperature : -20 to 75°C

Package : Tape carrier package (TCP)

Cascading multiple devices

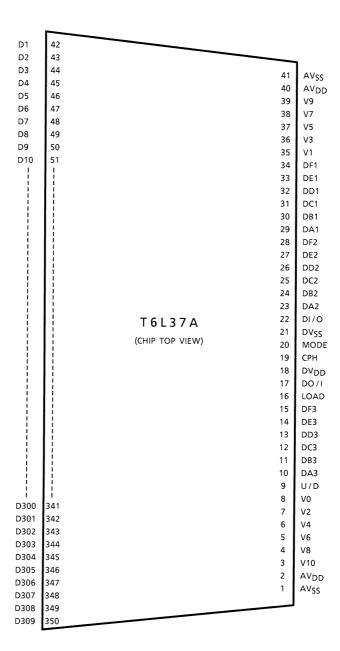


Block Diagram



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Pin Assignment



The above diagram shows the device's pin configuration only and does not necessarily correspond to the pad layout on the chip. Please contact Toshiba or our distributor for the latest TCP specification.

Pin Function

Pin Name	I/O			Function							
		Data transfer enable pin These pins, become active at the high signal, initiated the transferred data into the sampling register of the device. One is configured as an input and the other is configured as an output of which directions are determined by U/D as shown below.									
			U/D	DI/O	DO/I						
DI/O	1/0		Н	Input	Output						
DO/I	I/O		L	Output	Input						
		When the internal data is latched in When set for output The pin is used to	When set for input A high on DI/O or DO/I is latched into the internal logic synchronously with the rising edge of CPH. When the internal circuit is in standby state, the device is ready to transfer data. The grayscale data is latched in sequentially, starting at the next rise of CPH.								
U/D	I	This pin controls transferred sync When U/D is When U/D is	ransfer direction select pin This pin controls the direction in which the data is transferred into the sampling register. Data is transferred synchronously with each rising edge of CPH in one of the following sequences: When U/D is high, data is transferred in the order D1 to D3, D4 to D6, D7 to D9, When U/D is low, the direction is reversed to give D307 to D309, D304 to D306, D301 to D303,								
		Sampling clock input	-	e a DC-level voltage	that is either high or	IOW.					
СРН	l		This clock input is used to transfer grayscale data.								
DA1 to DA 3 DB1 to DB 3 DC1 to DC 3 DD1 to DD 3 DE1 to DE 3 DF1 to DF 3	I	rising edge of CF follows: Grayscale di = 32 × D (*) where n The rela DA1 DA2	The data inputs consist of 6-bit word for each three channel that are transferred in parallel at the rising edge of CPH. The relationship between the grayscale data and the weight of each bit is as								
MODE	I	When MODE not used. (Vo When MODE	E = high, 300-output-		in which case D151						
LOAD	1	the Load register outputs are simu	r synchronously at th Itaneously updated.	ad input, the data is tree rising edge of CPH.	. All 300 or 309 LCD						
V0 to V10		Conditions : AV _{SS} < V0	sed to input the volta $\leq V1 \leq V2 \leq V3 \leq V4$	age used for the DAC $4 \le V5 \le V6 \le V7 \le V8$ $4 \le V5 \le V4 \le V3 \le V6$	3 ≤ V9 ≤ V10 < AV _{DD}	or					
D1 to D309	0	LCD panel drive pins	3								
AV _{DD}		Analog power supply	/ pin								
AV _{SS}		Analog GND pin This pin must be	at the same potentia	al level as the digital (GND pin.						
DV _{DD}		Digital power supply	pin.								
DV _{SS}		Digital GND pin This pin must be	at the same potentia	al level as the analog	GND pin.						

Device Operation

(1) Starting data transfer

A high input to the data transfer enable pin (DI/O or DO/I) is latched into the internal logic synchronously with the rising edge of CPH, setting the device ready to transfer data. Data transfer starts at the next rise of CPH (see Fig. 1-1 and 2-1).

This enable pin must not be held for more than one CPH period.

(2) Data transfer method

The data is latched in from the grayscale bus to the sampling register (REG1) synchronously with each rising edge of CPH.

Grayscale data for three outputs are latched into the device simultaneously in one transfer.

Therefore, the data is latched in 300-output mode by performing 100 transfers, and data is latched in 309-output mode by performing 103 transfers. When the data loading is completed, the device enters a standby state.

(3) Terminating data transfer

in following a 1H period (see Fig. 1-2).

The data transfer enable pin (DO/I or DI/O) output goes high synchronously with the rising edge of CPH one clock period before the last data is latched in. It is held high until the next rise of CPH (see Fig. 1-1 and 2-1).

The output from this pin can be connected directly as input to the data transfer enable pin (DI/O or DO/I) of the next stage LCD driver. In this way, multiple devices can be easily cascaded to drive a large screen.

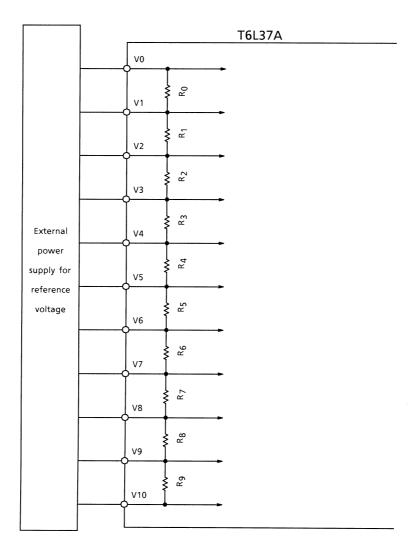
(4) Panel drive output

When a high voltage supplies to the load input, the data in the sampling register (REG1) is transferred to the load register (REG2) and the device starts updating output to the LCD panel drive pins. CPH must be held at the DC level for the duration from three CPH periods after a high input to LOAD is latched in until one clock period before CPH goes high after a high on the data transfer enable pin is latched

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(5) Reference power supply circuit

The connection between the device and the external reference power supply for Reference analog supply is configured with 7 or 8 resistors of the same specification in series (total of 64 resistor ladders).

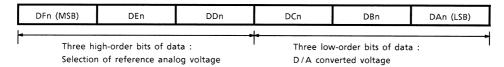


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(6) Grayscale data and output voltages

The LCD drive output voltages are determined by the grayscale values and the 11 reverence analog inputs line voltages (V0 to V10).

The three high-order data bits select a pair of reference analog voltages. Calculation of the output voltage involves multiplying a value derived from the selected reference analog values by a factor determined by the values of the three low-order bits and dividing by either seven or eight.

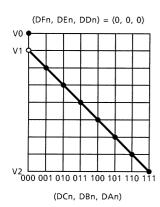


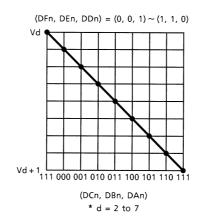
*n = 1, 2, 3

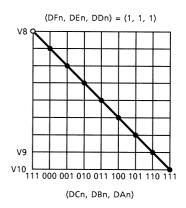
• Three high-order data bits

DF _n	DE _n	DD _n	Selected Reference Voltages
0	0	0	V0 or V1 and V2
0	0	1	V2 and V3
0	1	0	V3 and V4
0	1	1	V4 and V5
1	0	0	V5 and V6
1	0	1	V6 and V7
1	1	0	V7 and V8
1	1	1	V8 and V9 or V10

• Three low-order data bits







• Grayscale data and output voltages

															Note: $n = 1 \text{ to } 3$
Gray- scale Data	DFn	DEn	DDn	DCn	DBn	DAn	Output Voltage	Gray- scale Data	DFn	DEn	DDn	DCn	DBn	DAn	Output Voltage
00H	0	0	0	0	0	0	VO	20H	1	0	0	0	0	0	V6 + (V5 – V6) × 7/8
01H	0	0	0	0	0	1	V2 + (V1 – V2) × 6/7	21H	1	0	0	0	0	1	V6 + (V5 – V6) × 6/8
02H	0	0	0	0	1	0	V2 + (V1 – V2) × 5/7	22H	1	0	0	0	1	0	V6 + (V5 – V6) × 5/8
03H	0	0	0	0	1	1	V2 + (V1 – V2) × 4/7	23H	1	0	0	0	1	1	V6 + (V5 – V6) × 4/8
04H	0	0	0	1	0	0	V2 + (V1 – V2) × 3/7	24H	1	0	0	1	0	0	V6 + (V5 – V6) × 3/8
05H	0	0	0	1	0	1	$V2 + (V1 - V2) \times 2/7$	25H	1	0	0	1	0	1	$V6 + (V5 - V6) \times 2/8$
06H	0	0	0	1	1	0	V2 + (V1 – V2) × 1/7	26H	1	0	0	1	1	0	V6 + (V5 – V6) × 1/8
07H	0	0	0	1	1	1	V2	27H	1	0	0	1	1	1	V6
08H	0	0	1	0	0	0	V3 + (V2 – V3) × 7/8	28H	1	0	1	0	0	0	V7 + (V6 – V7) × 7/8
09H	0	0	1	0	0	1	V3 + (V2 – V3) × 6/8	29H	1	0	1	0	0	1	V7 + (V6 – V7) × 6/8
0AH	0	0	1	0	1	0	V3 + (V2 – V3) × 5/8	2AH	1	0	1	0	1	0	V7 + (V6 – V7) × 5/8
0BH	0	0	1	0	1	1	V3 + (V2 – V3) × 4/8	2BH	1	0	1	0	1	1	V7 + (V6 – V7) × 4/8
0CH	0	0	1	1	0	0	V3 + (V2 – V3) × 3/8	2CH	1	0	1	1	0	0	V7 + (V6 – V7) × 3/8
0DH	0	0	1	1	0	1	V3 + (V2 – V3) × 2/8	2DH	1	0	1	1	0	1	V7 + (V6 – V7) × 2/8
0EH	0	0	1	1	1	0	V3 + (V2 – V3) × 1/8	2EH	1	0	1	1	1	0	V7 + (V6 – V7) × 1/8
0FH	0	0	1	1	1	1	V3	2FH	1	0	1	1	1	1	V7
10H	0	1	0	0	0	0	V4 + (V3 – V4) × 7/8	30H	1	1	0	0	0	0	V8 + (V7 – V8) × 7/8
11H	0	1	0	0	0	1	V4 + (V3 – V4) × 6/8	31H	1	1	0	0	0	1	V8 + (V7 – V8) × 6/8
12H	0	1	0	0	1	0	V4 + (V3 – V4) × 5/8	32H	1	1	0	0	1	0	V8 + (V7 – V8) × 5/8
13H	0	1	0	0	1	1	V4 + (V3 – V4) × 4/8	33H	1	1	0	0	1	1	V8 + (V7 – V8) × 4/8
14H	0	1	0	1	0	0	V4 + (V3 – V4) × 3/8	34H	1	1	0	1	0	0	V8 + (V7 – V8) × 3/8
15H	0	1	0	1	0	1	V4 + (V3 – V4) × 2/8	35H	1	1	0	1	0	1	V8 + (V7 – V8) × 2/8
16H	0	1	0	1	1	0	V4 + (V3 – V4) × 1/8	36H	1	1	0	1	1	0	V8 + (V7 – V8) × 1/8
17H	0	1	0	1	1	1	V4	37H	1	1	0	1	1	1	V8
18H	0	1	1	0	0	0	V5 + (V4 – V5) × 7/8	38H	1	1	1	0	0	0	V9 + (V8 – V9) × 6/7
19H	0	1	1	0	0	1	V5 + (V4 – V5) × 6/8	39H	1	1	1	0	0	1	V9 + (V8 – V9) × 5/7
1AH	0	1	1	0	1	0	V5 + (V4 – V5) × 5/8	ЗАН	1	1	1	0	1	0	V9 + (V8 – V9) × 4/7
1BH	0	1	1	0	1	1	V5 + (V4 – V5) × 4/8	3ВН	1	1	1	0	1	1	V9 + (V8 – V9) × 3/7
1CH	0	1	1	1	0	0	V5 + (V4 – V5) × 3/8	3СН	1	1	1	1	0	0	V9 + (V8 – V9) × 2/7
1DH	0	1	1	1	0	1	V5 + (V4 – V5) × 2/8	3DH	1	1	1	1	0	1	V9 + (V8 – V9) × 1/7
1EH	0	1	1	1	1	0	V5 + (V4 – V5) × 1/8	3EH	1	1	1	1	1	0	V9
1FH	0	1	1	1	1	1	V5	3FH	1	1	1	1	1	1	V10

• Reference analog resistance rate ($R_0 = 2.31 \text{ k}\Omega$)

R ₀	R ₁	R ₂	R ₃	R ₄	R ₅	R ₆	R ₇	R ₈	R ₉
1.00	2.00	2.77	1.50	0.90	0.84	0.66	0.84	1.42	1.05



Timing Diagrams

• In 300-output mode

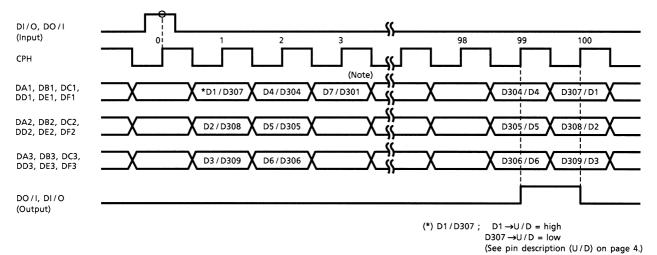


Fig. 1-1

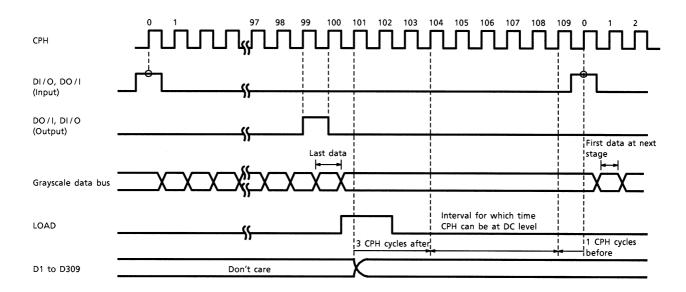


Fig. 1-2

Note: Except for D151 to D159



• In 309 output mode

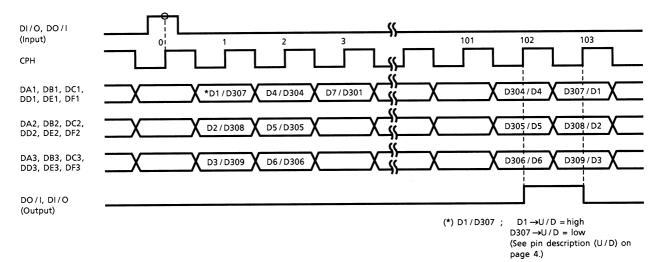


Fig. 2-1

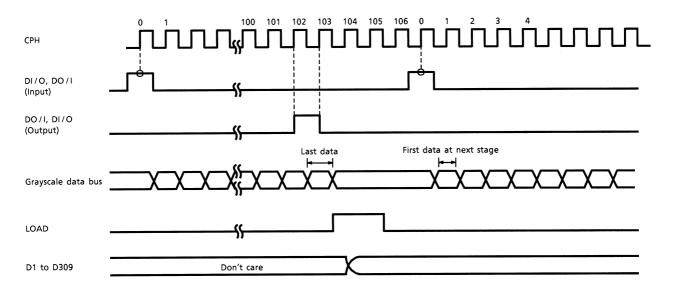


Fig. 2-2



Absolute Maximum Ratings (AV_{SS} = DV_{SS} = 0 V)

Characteristics	Symbol	Rating	Unit	Relevant Pin
Analog Supply Voltage	AV_{DD}	-0.3 to 6.5	V	_
Digital Supply Voltage	DV_DD	-0.3 to AV _{DD} + 0.3	٧	_
Input Voltage	V _{IN}	-0.3 to DV _{DD} + 0.3	V	_
Reference Analog Voltage	V (0: 10)	-0.3 to AV _{DD} + 0.3	V	V0 to V10
Storage Temperature	T _{stg}	-55 to 125	°C	_

Recommended Operating Conditions (AV_{SS} = DV_{SS} = 0 V)

Characteristics		Symbol	Test Condition	Rating	Unit	Relevant Pin	
Analog Supply Voltage		AV_{DD}	_	4.5 to 5.5	V	_	
Digital Supply Voltage		DV _{DD}	_	3.0 to 3.6	V	_	
Reference Analog Voltage-1	(Note 1)	V1 to V9	_	AV _{SS} + 0.1 to AV _{DD} – 0.1	V	_	
		V0	Case 1	V1 to AV _{DD}			
Reference Analog Voltage-2		٧٥	Case 2	Case 2 AV _{SS} to V1			
	(Note 1)	V10	Case 1	AV _{SS} to V9	V	_	
		V 10	Case 2	V9 to AV _{DD}			
Driver Unit Output Voltage		V _{OUT}	_	AV _{SS} + 0.1 to AV _{DD} – 0.1	V	D1 to D309	
Operating Temperature		T _{opr}	_	–20 to 75	°C	_	
Operating Frequency		f _{CPH}	_	DC to 55	MHz	CPH	
Output Load Capacitance		CL	_	150 (max)	pF / PIN	D1 to D309	

Note 1: The following shows the relative magnitude of each reference analog voltage:

For case 1

 $AV_{\mbox{\footnotesize SS}} < \mbox{\footnotesize V10}, \mbox{\footnotesize Vd} \leq \mbox{\footnotesize Vd} - \mbox{\footnotesize 1}, \mbox{\footnotesize V0} < \mbox{\footnotesize AV}_{\mbox{\footnotesize DD}} \mbox{\footnotesize (where d = 9 to 1)}$

• For case 2

 $AV_{SS} < V0$, $Vd \le Vd + 1$, $V10 < AV_{DD}$ (where d = 1 to 9)

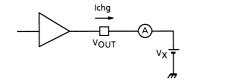
Electrical Characteristics

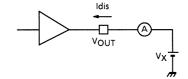
DC Characteristics (AV_{DD} = 4.5 to 5.5 V, DV_{DD} = 3.0 to 3.6 V, AV_{SS} = DV_{SS} = 0 V, Ta = -20 to 75°C)

Characte	ristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit	Relevant Pin		
Innut Voltage	Low Level	V _{IL}		_	0	-	0.3 × DV _{DD}	V	Logic input		
Input Voltage	High Level	V_{IH}		_	0.7 × DV _{DD}		DV _{DD}	•	Logic input		
	Low Level	V_{OL}		I _{OL} = 1.0 mA	DV _{SS}	_	DV _{SS} + 0.5	V			
Output Voltage	High Level	V _{OH}		I _{OH} = -1.0 mA	DV _{DD} - 0.5	_	DV _{DD}	V	Logic output		
		Ichg		_	_	_	-0.15				
Output Current	(Note 2)	Idis	_	V _{OUT} = 0 V AV _{DD} = 5 V V _X = 1 V	0.5		_	mA	D1 to D309		
Resistance between Reference Analog Voltage Pins		R_{GMA}	_	_		30	_	kΩ	V0 to V10		
Output Voltage Deviation		V_{DO}	_	_	_	±20	_	mV	D1 to D309		
Leakage Current		I _{IN}	_	_	-1.0	_	1.0	μΑ	Logic input		
Standby Current	t	ID _{STB}	_	fCPH = DC	-5.0	0.0	5.0	μΑ	DV _{DD}		
Current Conque	Al _{DD}		_	$\begin{array}{l} \text{fCPH} = 30 \text{ MHz} \\ 1\text{H} = 30 \mu\text{s}, \\ \text{no load} \\ \text{Checkerboard pattern} \\ \text{AV}_{DD} = 5.5 \text{ V} \end{array}$		4.0	7.0	mA	AV _{DD}		
Current Consum	Current Consumption (1)		t Consumption (1)		_	$\begin{array}{l} \text{fCPH} = 30 \text{ MHz} \\ 1\text{H} = 30 \mu\text{s}, \\ \text{no load} \\ \text{Checkerboard pattern} \\ \text{DV}_{DD} = 3.6 \text{ V} \end{array}$		6.0	8.0	ША	DV _{DD}
Current Consumption (2)		Al _{DD}		$\label{eq:fCPH} \begin{split} &\text{fCPH} = 20 \text{ MHz} \\ &\text{1H} = 26.4 \mu\text{s}, \\ &\text{no load} \\ &\text{Checkerboard pattern} \\ &\text{AV}_{DD} = 5.0 \text{ V} \end{split}$	_	3.5	6.0	mA	AV _{DD}		
		DI _{DD}	_	$\label{eq:fCPH} \begin{split} &\text{fCPH} = 20 \text{ MHz} \\ &1\text{H} = 26.4 \mu\text{s}, \\ &\text{no load} \\ &\text{Checkerboard pattern} \\ &\text{DV}_{DD} = 3.0 \text{ V} \end{split}$	_	2.5	5.5	ША	DV _{DD}		

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Note 2: V_X denotes the voltage applied to the LCD panel drive pin.

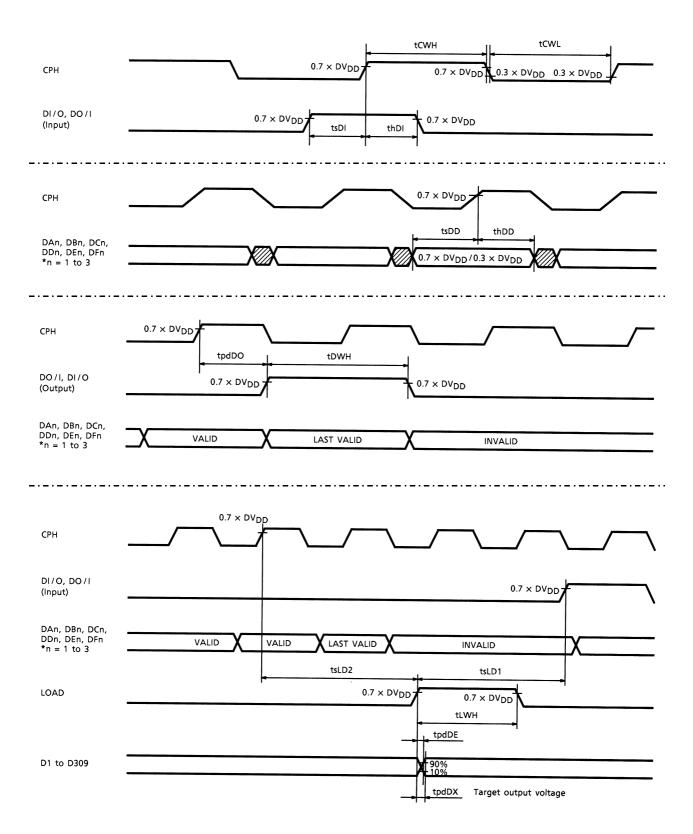






AC Characteristics (AV_{DD} = 4.5 to 5.5 V, DV_{DD} = 3.0 to 3.6 V, DV_{SS} = AV_{SS} = 0 V, Ta = -20 to 75°C)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
CPH Pulse Width H	tCWH	_	_	4.0	_	_	ns
CPH Pulse Width L	tCWL	_	_	4.0	_	_	ns
Enable Setup Time	tsDI	_	_	4.0	_	_	ns
Enable Hold Time	thDI	_	_	0	_	_	ns
Enable Pulse Width H	tDWH	_	_	_	1.0	_	CPH period
Data Setup Time	tsDD	_	_	4.0	_	_	ns
Data Hold Time	thDD	_	_	0	_	_	ns
Output Delay Time 1	tpdDO	_	C _L = 35 pF	_	_	14.0	ns
Output Delay Time 2	tpdDE	_	$C_L = 2 \text{ k}\Omega + 75 \text{ pF} \times 2$ Target output voltage ± $AV_{DD} \times 0.1$	_	_	3.0	μS
Output Delay Time 3	tpdDX	_	$C_L = 2 \text{ K}\Omega + 75 \text{ pF} \times 2$ Target output voltage	_	_	10.0	μS
LOAD Setup Time 1	tsLD1			1.0			CPH period
LOAD Setup Time 2	tsLD2	_	_	7.0	_	_	ns
LOAD Pulse Width H	tLWH	_	_	2.0	_	_	CPH period



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